

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

1. (currently amended) A method for electrically connecting a ~~first~~ printed circuit board of an electrical energy meter, and a second component, comprising:

inserting a wire pin through a through hole formed in the ~~first component~~ printed circuit board so that a first portion of the wire pin is located within the through hole and a second portion of the wire pin is located within a retaining feature formed at least in part by the second component; and

moving one of the ~~first~~ printed circuit board and the second component~~[[s]]~~ in relation to the other of the ~~first~~ printed circuit board and the second component~~[[s]]~~ so that the wire pin resiliently deflects thereby establishing a first contact force between the first portion of the wire pin and the ~~first component~~ printed circuit board, and a second contact force between the second portion of the wire pin and the second component.

2, 3. (canceled)

4. (withdrawn) The method of claim 1, wherein the second component is a printed circuit board and the retaining feature is a through hole formed in the printed circuit board.

5. (withdrawn) The method of claim 4, wherein the second component is a printed circuit board of an electrical-energy meter.

6. (original) The method of claim 1, wherein the second component is a contact blade and the retaining feature is a pocket formed by the contact blade and a projection located proximate the contact blade.

7. (currently amended) The method of claim 6, wherein the projection is formed on a base of ~~[[an]]~~ the electrical-energy meter.

8. (currently amended) The method of claim 1, wherein inserting a wire pin through a through hole formed in the ~~first component~~ printed circuit board comprises inserting the wire pin in a first direction, and moving one of the ~~first~~ printed circuit board and the second component~~[[s]]~~ in relation to the other of the ~~first~~ printed circuit board and the second component~~[[s]]~~ comprises moving the one of the ~~first~~ printed circuit board and the second component~~[[s]]~~ in relation to the other of the ~~first~~ printed circuit board and the second component~~[[s]]~~ in a second direction substantially perpendicular to the first direction.

9. (currently amended) The method of claim 1, wherein moving one of the ~~first~~ printed circuit board and the second component~~[[s]]~~ in relation to the other of the ~~first~~ printed circuit board and the second component~~[[s]]~~ so that the wire pin resiliently deflects comprises moving one of the ~~first~~ printed circuit board and the second component~~[[s]]~~ in relation to the other of the ~~first~~ printed circuit board and the second component~~[[s]]~~ so that the wire pin bends.

10. (original) The method of claim 1, further comprising substantially aligning the through hole with the retaining feature before inserting the wire pin.

11. (currently amended) The method of claim 10, wherein the moving one of the ~~first~~ printed circuit board and the second component[[s]] in relation to the other of the ~~first~~ printed circuit board and the second component[[s]] so that the wire pin resiliently deflects comprises substantially misaligning the through hole and the retaining feature.

12. (original) The method of claim 1, wherein the through hole is a plated through hole and the first contact force is established between the first portion of the wire and the plating of the through hole.

13. (currently amended) The method of claim 1, further comprising locking the one of the ~~first~~ printed circuit board and the second component[[s]] in position in relation to the other of the ~~first~~ printed circuit board and the second component[[s]] after moving the one of the ~~first~~ printed circuit board and the second component[[s]] in relation to the other of the ~~first~~ printed circuit board and the second component[[s]].

14. (currently amended) The method of claim 1, wherein inserting a wire pin through a through hole formed in the ~~first component~~ printed circuit board comprises dropping the wire pin through the through hole.

15. (currently amended) The method of claim 1, wherein moving one of the ~~first~~ printed circuit board and the second component[[s]] in relation to the other of the ~~first~~ printed circuit board and the second component[[s]] so that the wire pin resiliently deflects comprises moving the one of the ~~first~~ printed circuit board and the second component[[s]] in relation to the other of the ~~first~~ printed circuit board and the second component[[s]] so that the first portion of the wire is restrained by the ~~first component~~ printed circuit board and the second portion of the wire is restrained by the second component thereby causing the first portion of the wire to move in relation to the second portion of the wire in response to the movement of the ~~first component~~ printed circuit board in relation to the second component.

16. (currently amended) The method of claim 6, wherein the projection and the contact blade restrain the wire pin when the one of the ~~first~~ printed circuit board and the second component[[s]] is moved in relation to the other of the ~~first~~ printed circuit board and the second component[[s]].

17. (original) The method of claim 16, wherein the projection and the contact blade restrain the wire pin so that the wire pin pivots about the projection.

18. (withdrawn) A method for electrically connecting a first and a second component, comprising:

substantially aligning a first through hole formed in the first component with one of a second through hole formed in the second component and a pocket formed at least in part by the second component;

inserting a wire pin through the first through hole in a first direction so that a first portion of the wire pin is located within the first through hole and a second portion of the wire pin is located within one of the second through hole and the pocket; and

moving one of the first and the second components in a second direction in relation to the other of the first and the second components, the second direction being substantially perpendicular to the first direction, thereby causing one of the first and second portions of the wire pin to move in relation to the other of the first and second portions of the wire pin.

19. (withdrawn) The method of claim 18, wherein the first component is a printed circuit board.

20. (withdrawn) The method of claim 19, wherein the first component is a printed circuit board of an electrical-energy meter.

21. (withdrawn) The method of claim 18, wherein the second component is a printed circuit board.

22. (withdrawn) The method of claim 21, wherein the second component is a printed circuit board of an electrical-energy meter.

23. (withdrawn) The method of claim 18, wherein the second component is a contact blade.

24. (withdrawn) The method of claim 23, wherein the second component is a contact blade of an electrical-energy meter.

25. (withdrawn) The method of claim 18, wherein the pocket is defined by the contact blade and a projection.

26. (withdrawn) The method of claim 25, wherein the projection is formed on a base of an electrical-energy meter.

27. (withdrawn) The method of claim 18, wherein moving one of the first and the second components in a second direction in relation to the other of the first and the second components comprises moving one of the first and the second components in a second direction in relation to the other of the first and the second components so that the wire pin resiliently deflects thereby establishing a contact force between the wire pin and the first and second components.

28. (withdrawn) The method of claim 18, wherein moving one of the first and the second components in a second direction in relation to the other of the first and the second components comprises moving the one of the first and the second components in relation to the other of the first and the second components so that the first portion of the wire is restrained by the first component and the second portion of the wire is restrained by the

second component thereby causing the first portion of the wire to move in relation to the second portion of the wire.

29. (currently amended) A method for establishing electrical contact between a first printed circuit board of an electrical energy meter and a second component, comprising:

substantially aligning a first retaining feature defined at least in part by the ~~first component~~ printed circuit board with a second retaining feature defined at least in part by the second component so that the first and second retaining features can each receive a respective portion of a wire pin; and

substantially misaligning the first and second retaining features after the first and second retaining features have each received the respective portions of the wire pin so that the ~~first~~ printed circuit board and the second component[[s]] bend the wire pin and thereby establish contact forces between the ~~first component~~ printed circuit board and the wire pin, and the second component and the wire pin.

30. (currently amended) A method for electrically connecting a first printed circuit board of an electrical energy meter and a second component, comprising:

inserting a wire pin through a first retaining feature formed at least in part by the ~~first component~~ printed circuit board so that a first portion of the wire pin is located within the first retaining feature and a second portion of the wire pin is located within a retaining feature formed at least in part by the second component; and

moving one of the first printed circuit board and the second component[[s]] in relation to the other of the first printed circuit board and the second component[[s]] so that

the ~~first component~~ printed circuit board engages the first portion of the wire pin by way of the first retaining feature, and the second component engages the second portion of the wire pin by way of the second retaining feature thereby causing the first portion of the wire pin to move in relation to the second portion of the wire pin and bending the wire pin.

31-36. (canceled)

37. (new) A method for electrically connecting a first component and a contact blade, comprising:

inserting a wire pin through a through hole formed in the first component so that a first portion of the wire pin is located within the through hole and a second portion of the wire pin is located within a pocket formed by the contact blade and a projection formed on a base of an electrical energy meter and located proximate the contact blade; and

moving one of the first component and the contact blade in relation to the other of the first component and the contact blade so that the wire pin resiliently deflects thereby establishing a first contact force between the first portion of the wire pin and the first component, and a second contact force between the second portion of the wire pin and the contact blade.

38. (new) A method for electrically connecting a first component and a contact blade, comprising:

inserting a wire pin through a through hole formed in the first component so that a first portion of the wire pin is located within the through hole and a second portion of



the wire pin is located within a pocket formed by the contact blade and a projection located proximate the contact blade; and

moving one of the first component and the contact blade in relation to the other of the first component and the contact blade so that the wire pin resiliently deflects thereby establishing a first contact force between the first portion of the wire pin and the first component, and a second contact force between the second portion of the wire pin and the contact blade.

39. (new) A method for electrically connecting a first and a second component, comprising:

inserting a substantially straight wire pin through a through hole formed in the first component so that a first portion of the wire pin is located within the through hole and a second portion of the wire pin is located within a retaining feature formed at least in part by the second component; and

moving one of the first and the second components in relation to the other of the first and the second components so that the wire pin resiliently deflects thereby establishing a first contact force between the first portion of the wire pin and the first component, and a second contact force between the second portion of the wire pin and the second component.

40. (new) The method of claim 39, wherein moving one of the first and the second components in relation to the other of the first and the second components comprises moving one of the first and the second components in relation to the other of the first and the

second components while the wire pin is not fastened to the first component or the second component.

41. (new) The method of claim 39, wherein:

inserting a substantially straight wire pin through a through hole formed in the first component comprises inserting the substantially straight wire pin through the through hole substantially in a first direction; and

moving one of the first and the second components in relation to the other of the first and the second components comprises moving one of the first and the second components only in a direction substantially perpendicular to the first direction.

42. (new) The method of claim 39, wherein moving one of the first and the second components in relation to the other of the first and the second components so that the wire pin resiliently deflects comprises moving one of the first and the second components in relation to the other of the first and the second components to cause the wire pin to contact each of the first and second components at two locations on each of the first and second components.